

STN	Integrácia softvérového nástroja (FDI) Časť 1: Prehľad	STN EN IEC 62769-1 18 4012
------------	---	--

Field Device Integration (FDI) - Part 1: Overview

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 06/21

Obsahuje: EN IEC 62769-1:2021, IEC 62769-1:2021

Oznámením tejto normy sa od 12.03.2024 ruší
STN EN 62769-1 (18 4012) z decembra 2015

132878

EUROPEAN STANDARD

EN IEC 62769-1

NORME EUROPÉENNE

EUROPÄISCHE NORM

March 2021

ICS 35.100; 25.040.40; 35.100.05

Supersedes EN 62769-1:2015 and all of its amendments
and corrigenda (if any)

English Version

**Field Device Integration (FDI) - Part 1: Overview
(IEC 62769-1:2021)**Intégration des appareils de terrain (FDI) - Partie 1: Vue
d'ensemble
(IEC 62769-1:2021)Feldgeräteintegration (FDI) - Teil 1: Überblick
(IEC 62769-1:2021)

This European Standard was approved by CENELEC on 2021-03-12. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Croatia, Cyprus, the Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Republic of North Macedonia, Romania, Serbia, Slovakia, Slovenia, Spain, Sweden, Switzerland, Turkey and the United Kingdom.

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung**CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels**

EN IEC 62769-1:2021 (E)**European foreword**

The text of document 65E/758(F)/FDIS, future edition 2 of IEC 62769-1, prepared by SC 65E “Devices and integration in enterprise systems” of IEC/TC 65 “Industrial-process measurement, control and automation” was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62769-1:2021.

The following dates are fixed:

- latest date by which the document has to be implemented at national (dop) 2021-12-12 level by publication of an identical national standard or by endorsement
- latest date by which the national standards conflicting with the (dow) 2024-03-12 document have to be withdrawn

This document supersedes EN 62769-1:2015 and all of its amendments and corrigenda (if any).

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CENELEC shall not be held responsible for identifying any or all such patent rights.

Endorsement notice

The text of the International Standard IEC 62769-1:2021 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 61804-3	NOTE Harmonized as EN IEC 61804-3
IEC 61804-4	NOTE Harmonized as EN IEC 61804-4
IEC 61804-5	NOTE Harmonized as EN IEC 61804-5
IEC 62443 series	NOTE Harmonized as EN IEC 62443 series
IEC 62453 series	NOTE Harmonized as EN 62453 series
IEC 62541 series	NOTE Harmonized as EN IEC 62541 series
IEC 62769-2	NOTE Harmonized as EN 62769-2
IEC 62769-3	NOTE Harmonized as EN 62769-3
IEC 62769-4	NOTE Harmonized as EN 62769-4
IEC 62769-5	NOTE Harmonized as EN 62769-5
IEC 62769-6	NOTE Harmonized as EN 62769-6
IEC 62769-7	NOTE Harmonized as EN 62769-7

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC/TR 62541-1	-	OPC Unified Architecture - Part 1: Overview and concepts	CLC/TR 62541-1	-
IEC 62541-3	-	OPC Unified Architecture - Part 3: Address Space Model	EN IEC 62541-3	-
IEC 62541-4	-	OPC Unified Architecture - Part 4: Services	EN IEC 62541-4	-
IEC 62541-5	-	OPC Unified Architecture - Part 5: Information Model	EN IEC 62541-5	-
IEC 62541-100	-	OPC Unified Architecture - Part 100: Device Interface	EN 62541-100	-



IEC 62769-1

Edition 2.0 2021-02

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Field device integration (FDI) –
Part 1: Overview**

**Intégration des appareils de terrain (FDI) –
Partie 1: Vue d'ensemble**



**THIS PUBLICATION IS COPYRIGHT PROTECTED****Copyright © 2021 IEC, Geneva, Switzerland**

All rights reserved. Unless otherwise specified, no part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from either IEC or IEC's member National Committee in the country of the requester. If you have any questions about IEC copyright or have an enquiry about obtaining additional rights to this publication, please contact the address below or your local IEC member National Committee for further information.

Droits de reproduction réservés. Sauf indication contraire, aucune partie de cette publication ne peut être reproduite ni utilisée sous quelque forme que ce soit et par aucun procédé, électronique ou mécanique, y compris la photocopie et les microfilms, sans l'accord écrit de l'IEC ou du Comité national de l'IEC du pays du demandeur. Si vous avez des questions sur le copyright de l'IEC ou si vous désirez obtenir des droits supplémentaires sur cette publication, utilisez les coordonnées ci-après ou contactez le Comité national de l'IEC de votre pays de résidence.

IEC Central Office
3, rue de Varembé
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
info@iec.ch
www.iec.ch

About the IEC

The International Electrotechnical Commission (IEC) is the leading global organization that prepares and publishes International Standards for all electrical, electronic and related technologies.

About IEC publications

The technical content of IEC publications is kept under constant review by the IEC. Please make sure that you have the latest edition, a corrigendum or an amendment might have been published.

IEC publications search - webstore.iec.ch/advsearchform

The advanced search enables to find IEC publications by a variety of criteria (reference number, text, technical committee, ...). It also gives information on projects, replaced and withdrawn publications.

IEC Just Published - webstore.iec.ch/justpublished

Stay up to date on all new IEC publications. Just Published details all new publications released. Available online and once a month by email.

IEC Customer Service Centre - webstore.iec.ch/csc

If you wish to give us your feedback on this publication or need further assistance, please contact the Customer Service Centre: sales@iec.ch.

IEC online collection - oc.iec.ch

Discover our powerful search engine and read freely all the publications previews. With a subscription you will always have access to up to date content tailored to your needs.

Electropedia - www.electropedia.org

The world's leading online dictionary on electrotechnology, containing more than 22 000 terminological entries in English and French, with equivalent terms in 18 additional languages. Also known as the International Electrotechnical Vocabulary (IEV) online.

A propos de l'IEC

La Commission Electrotechnique Internationale (IEC) est la première organisation mondiale qui élabore et publie des Normes internationales pour tout ce qui a trait à l'électricité, à l'électronique et aux technologies apparentées.

A propos des publications IEC

Le contenu technique des publications IEC est constamment revu. Veuillez vous assurer que vous possédez l'édition la plus récente, un corrigendum ou amendement peut avoir été publié.

Recherche de publications IEC - webstore.iec.ch/advsearchform

La recherche avancée permet de trouver des publications IEC en utilisant différents critères (numéro de référence, texte, comité d'études, ...). Elle donne aussi des informations sur les projets et les publications remplacées ou retirées.

IEC Just Published - webstore.iec.ch/justpublished

Restez informé sur les nouvelles publications IEC. Just Published détaille les nouvelles publications parues. Disponible en ligne et une fois par mois par email.

Service Clients - webstore.iec.ch/csc

Si vous désirez nous donner des commentaires sur cette publication ou si vous avez des questions contactez-nous: sales@iec.ch.

IEC online collection - oc.iec.ch

Découvrez notre puissant moteur de recherche et consultez gratuitement tous les aperçus des publications. Avec un abonnement, vous aurez toujours accès à un contenu à jour adapté à vos besoins.

Electropedia - www.electropedia.org

Le premier dictionnaire d'électrotechnologie en ligne au monde, avec plus de 22 000 articles terminologiques en anglais et en français, ainsi que les termes équivalents dans 16 langues additionnelles. Egalement appelé Vocabulaire Electrotechnique International (IEV) en ligne.



IEC 62769-1

Edition 2.0 2021-02

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Field device integration (FDI) –
Part 1: Overview**

**Intégration des appareils de terrain (FDI) –
Partie 1: Vue d'ensemble**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

COMMISSION
ELECTROTECHNIQUE
INTERNATIONALE

ICS 25.040.40; 35.100.05

ISBN 978-2-8322-9307-2

**Warning! Make sure that you obtained this publication from an authorized distributor.
Attention! Veuillez vous assurer que vous avez obtenu cette publication via un distributeur agréé.**

CONTENTS

FOREWORD	4
INTRODUCTION	6
1 Scope	7
2 Normative references	7
3 Terms, definitions, abbreviated terms and conventions	7
3.1 Terms and definitions	7
3.2 IEC TR 62541-1 terms (OPC UA)	10
3.3 IEC 62541-3 (OPC UA) terms	10
3.4 IEC 62541-4 (OPC UA) terms	11
3.5 IEC 62541-5 (OPC UA) terms	11
3.6 IEC 62541-100 (OPC UA for Devices) terms	11
3.7 Abbreviated terms	12
3.8 Conventions	12
4 Background	12
4.1 Motivation	12
4.2 Electronic Device Description Language (EDDL)	13
4.3 Field Device Tool (FDT [®])	13
4.4 OPC Unified Architecture (OPC UA)	14
5 Architecture	14
5.1 Overview	14
5.2 FDI Packages	15
5.3 FDI Client	16
5.4 FDI Server	16
5.5 FDI Communication Server	17
5.6 User Interface tiering	17
5.7 FDI security considerations	17
5.8 Redundancy	18
6 Deployment	18
6.1 Overview	18
6.2 Engineering, operator and maintenance stations	19
6.3 FDI Server	19
6.4 FDI Communication Servers	19
6.5 Device Tools	19
6.6 Third-party Tools	19
6.7 Handheld Tools	19
6.8 Generic OPC UA Clients	19
7 FDI Host	19
7.1 Overview	19
7.2 FDI Host Variants and Entities	20
7.3 FDI Host Facets	20
8 Life-cycle model	21
8.1 Overview	21
8.2 Identification mechanism	21
8.3 Versioning mechanism	22
8.3.1 Version levels	22

8.3.2	FDI Technology Version	22
8.3.3	Forward compatibility.....	25
Annex A (informative)	FDI life-cycle concept summary.....	27
A.1	General.....	27
A.2	Life-cycle relevant topics (references).....	27
Annex B (informative)	Issue reporting	28
Bibliography	29
Figure 1	– FDI architecture diagram.....	15
Figure 2	– Typical deployment scenario	18
Figure 3	– FDI Technology Version dependencies	23
Table 1	– FDI Host Variants and possible Facets	20
Table 2	– FDI Host Facets and related FDI Entities.....	21
Table 3	– Summary of influences on the FDI Technology Version	25
Table 4	– Combinations of Minor Versions that require special handling	25
Table A.1	– Life-cycle aspects as part of the FDI technology	27
Table A.2	– Life-cycle aspects as part of products and services provided with the FDI technology	27

INTERNATIONAL ELECTROTECHNICAL COMMISSION

FIELD DEVICE INTEGRATION (FDI) –

Part 1: Overview

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC itself does not provide any attestation of conformity. Independent certification bodies provide conformity assessment services and, in some areas, access to IEC marks of conformity. IEC is not responsible for any services carried out by independent certification bodies.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- 9) Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 62769-1 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

This second edition cancels and replaces the first edition published in 2015. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) support for generic protocol extension for faster adoption of other technologies;
- b) digital signature now include trusted timestamping for long term validation of FDI Package;
- c) support of new protocols.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
65E/758/FDIS	65E/768/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

INTRODUCTION

The IEC 62769 series has the general title *Field Device Integration (FDI)* and the following parts:

- Part 1: Overview
- Part 2: FDI Client
- Part 3: FDI Server
- Part 4: FDI Packages
- Part 5: FDI Information Model
- Part 6: FDI Technology Mapping
- Part 7: FDI Communication Devices
- Part 100: Profiles – Generic Protocol Extensions
- Part 101-1: Profiles – Foundation Fieldbus H1
- Part 101-2: Profiles – Foundation Fieldbus HSE
- Part 103-1: Profiles – PROFIBUS
- Part 103-4: Profiles – PROFINET
- Part 109-1: Profiles – HART and WirelessHART
- Part 115-2: Profiles – Protocol-specific Definitions for Modbus RTU
- Part 150-1: Profiles – ISA 100.11a

FIELD DEVICE INTEGRATION (FDI) –

Part 1: Overview

1 Scope

This part of IEC 62769 describes the concepts and overview of the Field Device Integration (FDI) specifications. The detailed motivation for the creation of this technology is also described (see 4.1). Reading this document is helpful to understand the other parts of this multi-part standard.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC TR 62541-1, *OPC Unified Architecture – Part 1: Overview and concepts*

IEC 62541-3, *OPC Unified Architecture – Part 3: Address Space Model*

IEC 62541-4, *OPC Unified Architecture – Part 4: Services*

IEC 62541-5, *OPC Unified Architecture – Part 5: Information Model*

IEC 62541-100, *OPC Unified Architecture – Part 100: Device Interface*

koniec náhľadu – text ďalej pokračuje v platenej verzii STN